

FEATURES

- | Surface Mounting Design 4.0*3.5*3.5mm
- | High Current Handling Capability 3000A @ 8/20 μ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



4.0*3.5*3.5mm



Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 700	V
	At 1kV/μs	Typical values of distribution ≤ 600	V
Impulse Discharge Current 2)	8/20μs	3000	A
Insulation Resistance	DC=50V	≥ 1	GΩ
Capacitance at 1MHz	$V_{DC}=0.5V$	≤ 0.8	pF
Operating And Storage Temperature		-40-125	°C

1) In ionized mode

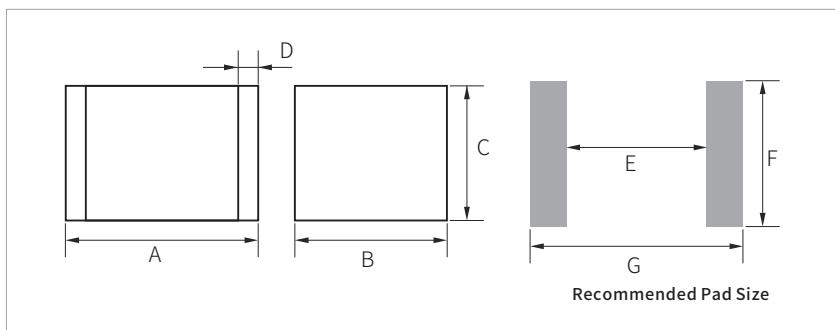
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering:10s, 1time

NOTE:Up-screen program can be specified by customer's request via contacting Semiware service

DIMENSIONS AND RECOMMENDED SOLDERING PAD



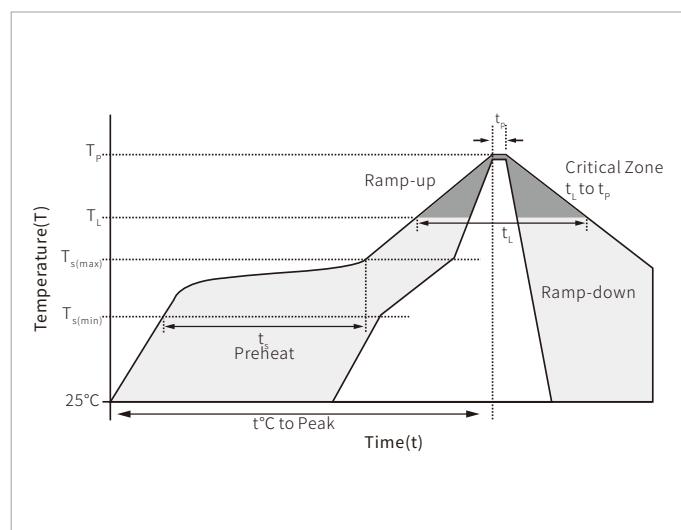
Ref.	mm
A	4.0±0.3mm
B	3.5±0.3mm
C	3.5±0.2mm
D	0.4mm
E	3.20mm
F	3.50mm
G	5.20mm

SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4-6 seconds

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak	$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_s)	60 – 150 seconds
Peak Temperature (T_p)	260°C	
Time within 5°C of actual peak Temperature (t_p)	20-40 seconds	
Ramp-down Rate	6°C/second max	
Time 25°C to peak Temperature (T_p)	8 minutes max.	
Do not exceed	260°C	



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG4035B090	4.0*3.5*3.5mm	2500PCS	13"

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By QR Code

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Wechat

To find your local partner within Semiware's global website: www.semiware.com

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